

THYRISTORS 03P4MG,03P6MG

300 mA HIGH-WITHSTANDING-VOLTAGE MOLD SCR

DESCRIPTION

The 03P4MG and 03P6MG are P-gate fully diffused mold SCRs with an average on-state current of 300 mA. The repeat peak off-state voltages (and reverse voltages) are 400 and 600 V.

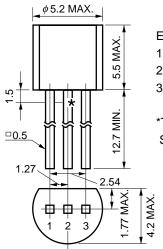
FEATURES

- 400 and 600 V high-withstanding-voltage series of products
- The non-repetitive withstanding voltage is a high 700 V, making it easy to harmonize the rise voltage of the surge absorber.
- High-sensitivity thyristor (Igt = 3 to 50 μ A)
- Employs flame-retardant epoxy resin (UL94V-0)

APPLICATIONS

Leakage breakers, SSRs, various type of alarms, consumer electronic equipments and automobile electronic components

PACKAGE DRAWING (Unit: mm)



Electrode connection

- 1: Gate
- 2: Anode
- 3: Cathode

*Tc test bench-mark Standard weight: 0.3 g

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

	Parameter	Symbol	Ratings		Unit	Remarks
		·	03P4MG	03P6MG		
	Non-repetitive Peak Reverse Voltage	VRSM	700	700	V	$R_{GK} = 1 k\Omega$
	Non-repetitive Peak Off-state Voltage	VDSM	700	700	V	$R_{GK} = 1 k\Omega$
www.DataS	Repetitive Peak Reverse Voltage	VRRM	400	600	V	$R_{GK} = 1 k\Omega$
	Repetitive Peak Off-state Voltage	VDRM	400	600	V	$R_{GK} = 1 k\Omega$
	Average On-state Current	I _{T(AV)}	300 (T _A = 30°C, Single half-wave, θ = 180°)			Refer to Figure 10.
	Effective On-state Current I _{T(RMS)} 470		70	mA	-	
*	Surge On-state Current	nt ITSM 8 (f = 50 Hz, Sine half-wave, 1 cycle)		half-wave, 1 cycle)	Α	Refer to Figure 2.
	Fusing Current	∫i⊤²dt	$0.15 (1 \text{ ms} \le t \le 10 \text{ ms})$		A ² s	-
	Critical Rate of On-state Current of Rise	dl⊤/dt	20		A/μs	-
	Peak Gate Power Dissipation	Рсм	100 (f ≥ 50 Hz, Duty ≤ 10%) 10		mW	Refer to Figure 3.
	Average Gate Power Dissipation	P _{G(AV)}			mW	Refer to Figure 3.
	Peak Gate Forward Current	Iгдм	100 (f ≥ 50 Hz, Duty ≤ 10%)		mA	-
	Peak Gate Reverse Voltage	VRGM	6		V	-
	Junction Temperature	Tj	-40 to +125		°C	_
	Storage Temperature	age Temperature T _{stg} -55 to +150				_

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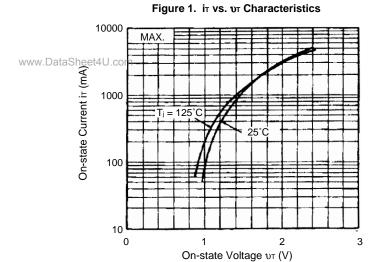
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ELECTRICAL CHARACTERISTICS (T_j = 25°C, R_{GK} = 1 k Ω)

Parameter	Symbol	Conditions		Specifications			Unit	Remarks
				MIN.	TYP.	MAX.		
Non-repetitive Peak Reverse	IRRM	Vrm = Vrrm	T _j = 25°C	_	_	10	μΑ	_
Current			T _j = 125°C	_	_	100	μΑ	-
Non-repetitive Peak Off-state	IDRM	VDM = VDRM	T _j = 25°C	_	_	10	μΑ	-
Current			T _j = 125°C	_	_	100	μΑ	_
Critical Rate-of-rise of Off-state	dV⊳/dt	$T_j = 125^{\circ}C$, $V_{DM} = \frac{2}{3}V_{DRM}$		10	_	_	V/μs	-
Voltage		3						
On-state Voltage	VT	I _T = 4 A		-	-	2.2	V	Refer to Figure 1.
Gate Trigger Current	Іст	$V_{DM} = 6 \text{ V}, \text{ RL} = 100 \Omega$		3	-	50	μΑ	_
Gate Trigger Voltage	V _{GT}	$V_{DM} = 6 \text{ V}, \text{ RL} = 100 \Omega$		_	_	0.8	V	_
Gate Non-trigger Voltage	V _{GD}	$T_j = 125^{\circ}C, V_{DM} = \frac{V_{DRM}}{2}$		0.2	-	-	V	_
Holding Current	Ін	V _{DM} = 24 V, I _{TM} = 4 A		_	_	5	mA	_
Turn-off Time	t q	$T_j = 125$ °C, $I_T = 200$ mA,		-	60	_	μs	_
		$dIR/dt = 15 A/\mu s$, V	R ≥ 25 V,					
		$V_{DM} = \frac{2}{3} V_{DRM}, dV_{D}/dt = 10 V/\mu s$						
Thermal Resistance	Rth(j-C)	Junction-to-case DC		_	_	50	°C/W	Refer to Figure 14.
	Rth(j-A)	Junction-to-ambient DC		_	_	230	°C/W	Refer to Figure 14.

TYPICAL CHARACTERISTICS (TA = 25°C)



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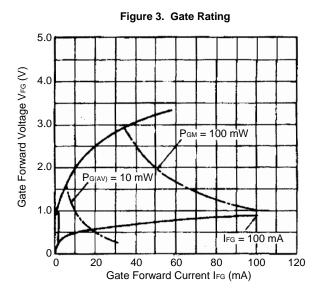
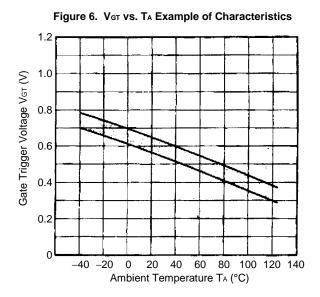
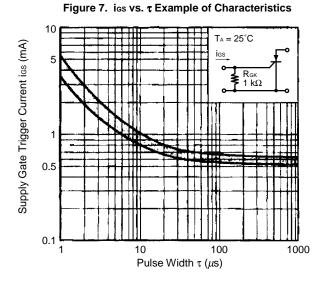


Figure 4. Example of Gate Characteristics 1.2 Gate Trigger Voltage Vg⊤ (V) 1.0 0°C 8.0 0.6 0.4 0.2 0 0 50 100 150 300 350 200 250 Gate Trigger Current Igt (µA)





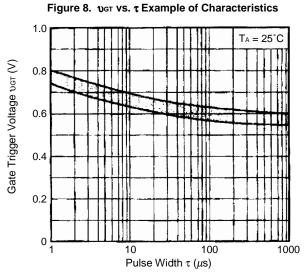


Figure 9. PT(AV) vs. IT(AV) Characteristics

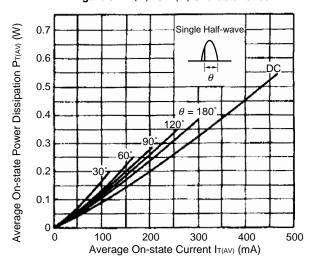


Figure 10. TA vs. IT(AV) Characteristics

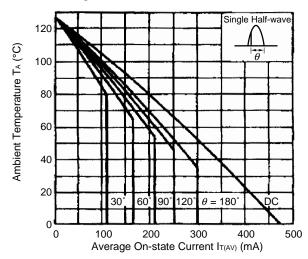


Figure 11. P_{T(AV)} vs. I_{T(AV)} Characteristics

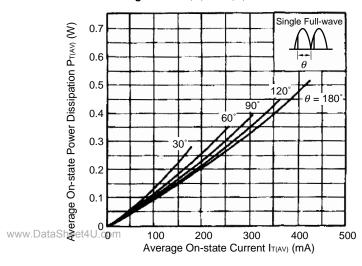


Figure 12. TA vs. IT(AV) Characteristics

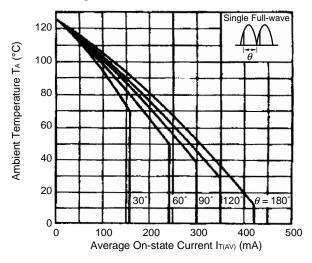
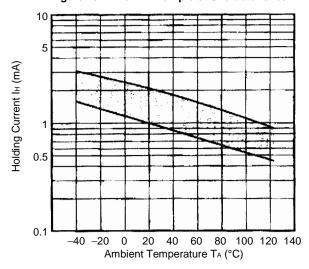
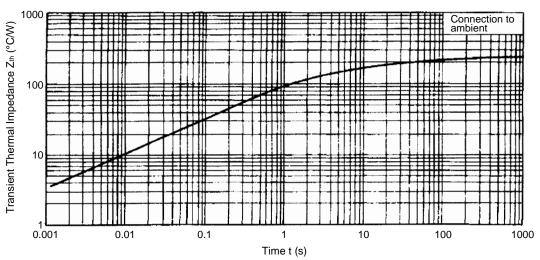


Figure 13. In vs. TA Example of Characteristics







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